

A

B

C

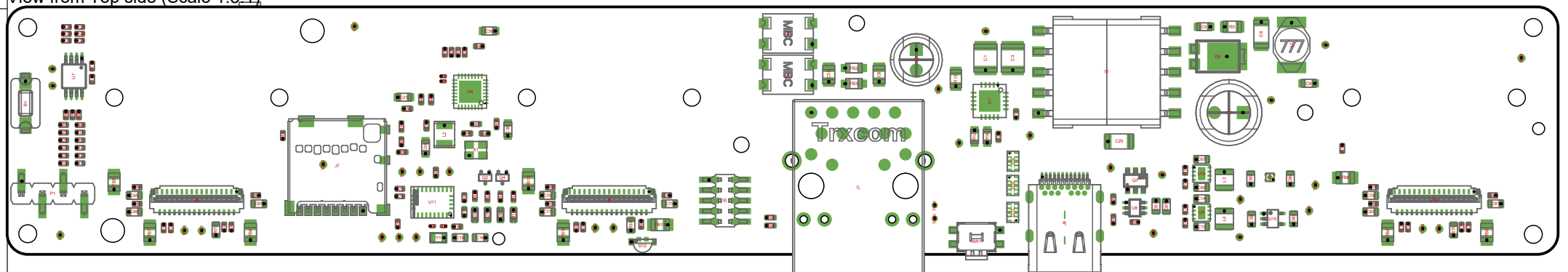
D

E

ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.

View from Top side (Scale 1.5:1)



Title: **BC2087**

Number: D2088000 Revision: R3M1
E3

Date: 08/06/2023 Sheet: 1 of 3

Drawn by: Boris Chou / Blaz
Kvas

LUXonjs

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A

B

C

D

E

A

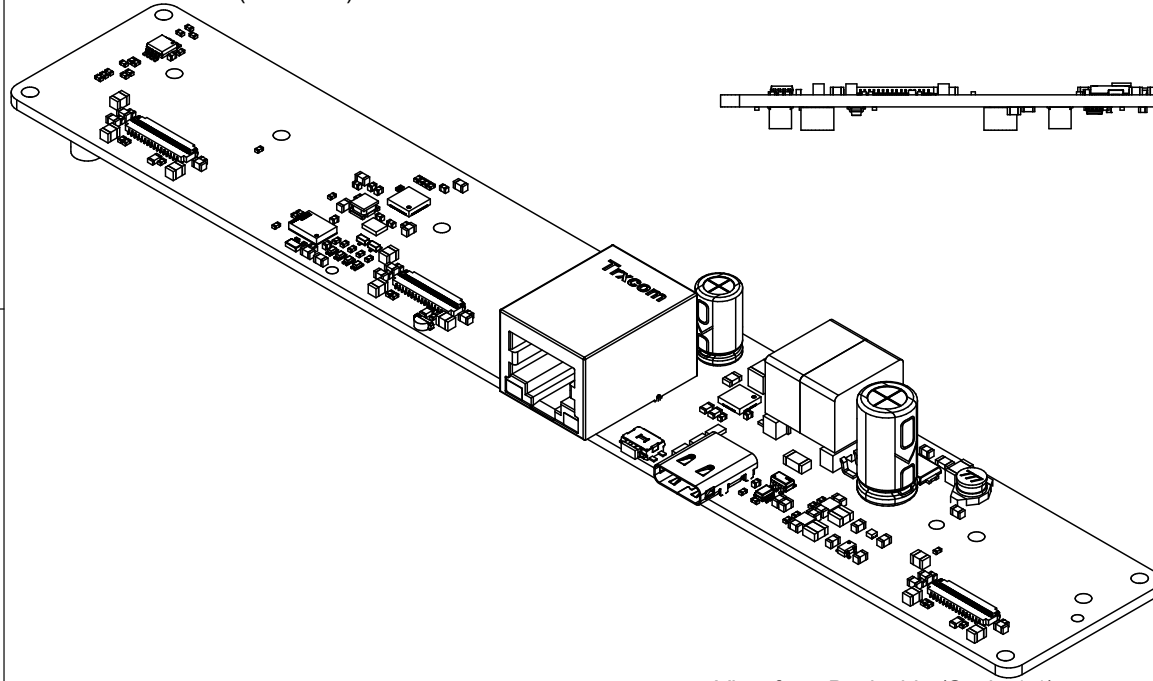
B

C

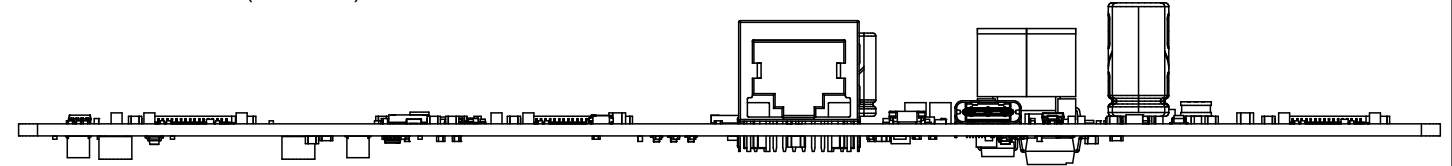
D

E

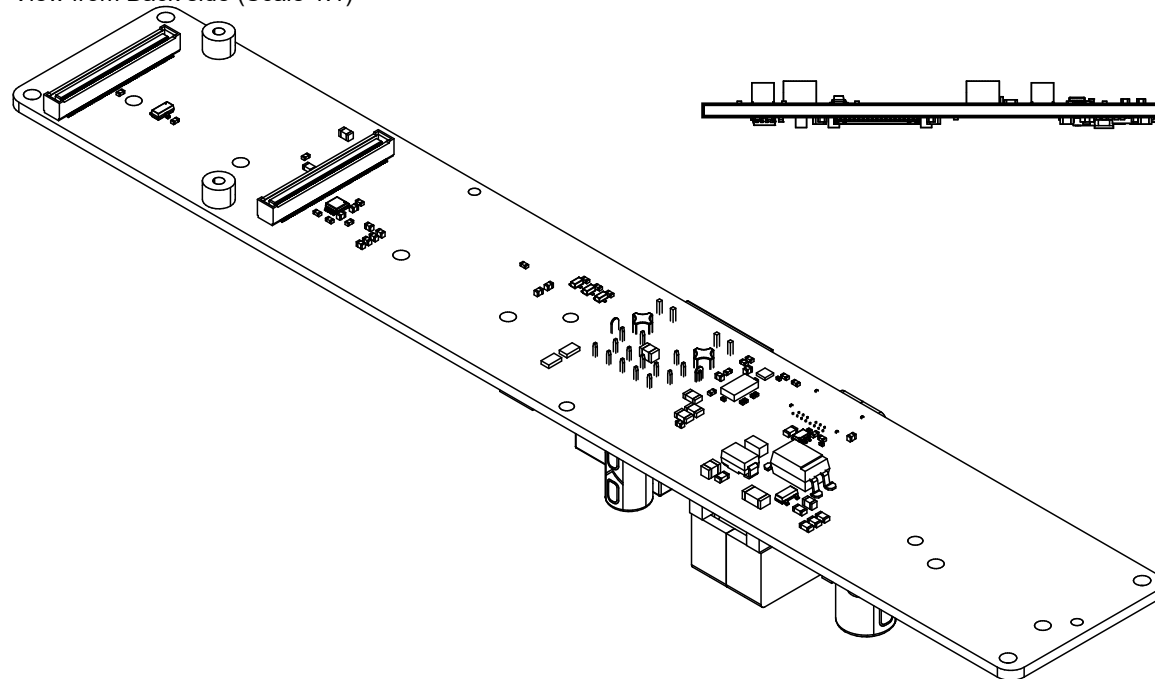
View from Front side (Scale 1:1)



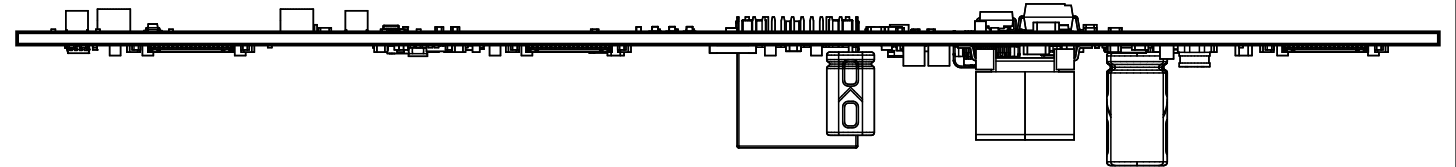
View from Front side (Scale 1:1)



View from Back side (Scale 1:1)



View from Back side (Scale 1:1)

Title: **BC2087**

Number: D2088000

Revision: R3M1
E3

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Sheet: 3 of 3

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